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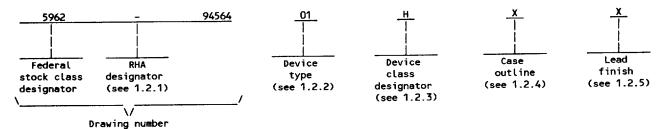
DESC FORM 193

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1 SCOPE

- 1.1 <u>Scope</u>. This drawing forms a part of a one part one part number documentation system (see 6.6 herein). This drawing describes device requirements for hybrid microcircuits to be processed in accordance with MIL-H-38534. Two product assurance classes, military high reliability (device class H) and space application (device class K) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes H and K RHA marked devices shall meet the MIL-H-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type

Generic number

O1 MHP27015D DC-DC Converter, 65 W, ±15 V output

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device requirements documentation

H or K

Certification and qualification to MIL-H-38534

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Y	See figure 1	12	Flange mount

1.2.5 <u>Lead finish</u>. The lead finish shall be as specified in MIL-H-38534 for classes H and K. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-95564
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 2

DESC FORM 193A JUL 94

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1.3 <u>Absolute maximum ratings</u> . <u>1</u> /							
Input voltage range <u>2</u> /	18 W +300°C	o +450 v dc 150°C					
1.4 Recommended operating conditions.							
Input voltage range	≤ 65 W	to +400 V dc 125°C					
2. APPLICABLE DOCUMENTS							
2.1 <u>Government specification, standards, and handbook</u> . standards, and handbook of the issue listed in that issue of Standards specified in the solicitation, form a part of the	of the Departmen	t of Defense Index of Spec	ifications and				
SPECIFICATION							
MILITARY							
MIL-H-38534 - Hybrid Microcircuits, General Specia	fication for.						
STANDARDS							
MILITARY							
MIL-STD-883 - Test Methods and Procedures for Microelectronics. MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.							
HANDBOOK							
MILITARY	MILITARY						
MIL-HDBK-780 – Standardized Military Drawings.							
(Copies of the specification, standards, and handbook rec acquisition functions should be obtained from the contracti	quired by manufac ing activity or a	cturers in connection with as directed by the contrac	specific ting activity.)				
2.2 Order of precedence. In the event of a conflict bet herein, the text of this drawing shall take precedence.	ween the text of	f this drawing and the ref	erences cited				
maximum levels may degrade performance and affect relia 2/ An undervoltage lockout circuit shuts the unit off when	 Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability. An undervoltage lockout circuit shuts the unit off when the input voltage drops to approximately 120 volts. Operation of the unit between 120 volts and 160 volts is non-destructive at reduced output power, but performance 						
is not guaranteed.		part part	, and por tor marrow				
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STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		5962-95564				
DAYTON, OHIO 45444		REVISION LEVEL	SHEET 3				
DESC FORM 193A JUL 94							

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3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-H-38534 and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-H-38534 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-H-38534. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in QML-38534.
- 3.6 <u>Manufacturer eligibility</u>. In addition to the general requirements of MIL-H-38534, the manufacturer of the part described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, produced on the certified line, for each device type listed herein. The data should also include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DESC-EC) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance submitted to DESC-EC shall affirm that the manufacturer's product meets the requirements of MIL-H-38534 and the requirements herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-H-38534 shall be provided with each lot of microcircuits delivered to this drawing.
 - 4. QUALITY ASSURANCE PROVISIONS
 - 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-H-38534.
 - 4.2 <u>Screening</u>. Screening shall be in accordance with MIL-H-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DESC-EC or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-95564
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 4

DESC FORM 193A JUL 94

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Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{IN} = 270 V dc ± 1 V dc	Group A subgroups	Device type	Limits		Unit	
		V _{IN} = 270 V dc ± 1 V dc no external sync unless otherwise specified			 Min	Max	 	
Output voltage	V _{OUT}	 I _{OUT} = ±2.17 A, (main)	11	01	+14.85	+15.15	V dc	
	İ		2,3	.	+14.55	+15.45	<u>. </u>	
		I _{OUT} = ±2.17 A, (dual)	1		-14.77	-15.23		
			2,3	<u> </u>	-14.47	-15.53		
Output current 7/	^I out	V _{IN} = 160 V dc to 400 V dc, sum of both outputs	1,2,3	01	0.0	4.34	A	
Output ripple voltage	V _{RIP}	 I _{OUT} = ±2.17 A, BW = 10 kHz to 2 MHz	11	01		100	mV p-p	
		BW = IU KHZ TO 2 MHZ	2,3			150		
Line regulation	VRLINE	 I _{OUT} = ±2.17 A, (main) V _{IN} = 160 V dc to 400 V dc 	 1,2,3 	 01 		 150 	mV	
		I _{OUT} = ±2.17 A, (dual) V _{IN} = 160 V dc to 400 V dc	 			 150 		
Load regulation	VR _{LOAD}	I _{OUT} = 0 to ±2.17 A, (main)	1,2,3	 01 		150	mV	
		I _{OUT} = 0 to ±2.17 A, (dual)	[150		
Input current	IIN	I _{OUT} = 0 A, inhibit (pins 3 and 4) open	1,2,3	01		20	mA	
		I _{OUT} = 0 A, inhibit 1 (pin 4) tied to input return (pin 2)	! 	 		10		
		 I _{OUT} = 0 A, inhibit 2 (pin 3) tied to output return (pin 8)	 	 		15		
Input ripple current	I _{RIP}	 I _{OUT} = ±2.17 A, BW = 10 kHz to 10 MHz	11	01		45	mA p-p	
		BW = 10 kHz to 10 MHz	2,3		<u> </u>	50		
Efficiency	 Eff	I _{OUT} = ±2.17 A	11	01	84	1	%	
			2,3		83			
Switching frequency	 Fs	 I _{OUT} = ±2.5 A	4,5,6	01	 525 	 675 	 kHz 	
See footnotes at end o	f table.				•		•	
	STANDAR	DRAWING	SIZE A				5962-9556	
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	i .	Conditions $-55^{\circ}C \leq T_C \leq +125^{\circ}C$ $V_{IN} = 270 \text{ V dc} \pm 1 \text{ V dc}$		Group A subgroups	Group A Device subgroups type		imits	Unit	
	5 - 	no ex	70 V dc ± 1 V dc kternal sync nerwise specified			Min	Max		
hort circuit current	I sc	V _{OUT} < 1.0	V dc,	1,2,3	01		9	A	
nternal power	PD	Pin - Pout		1	01		16_	w	
dissipation short circuit				2,3	<u> </u>		18		
oad fault recovery <u>1</u> /	Tr _{LF}	I _{OUT} = ±2.17 A		4,5,6	01		20	ms	
urn-on delay time	TonD	 I _{OUT} = ±2.17 A, V _{IN} = 0 V dc to 270 V dc		4,5,6	01		 20 	ms	
Turn-on overshoot 1/	Vtonos	I _{OUT} = ±2.17 A, V _{IN} = 0 V dc to 270 V dc		4	01		 ±150 	mV pk	
Output response to step	VTLOAD	I _{OUT} = ±1.09 A to ±2.17 A I _{OUT} = ±2.17 A to ±1.09 A		4,5,6	01		900	mV pk	
changes 2/				Í !			900		
Recovery time step transient Load	TTLOAD	$I_{OUT} = \pm 1.09 \text{ A to } \pm 2.17 \text{ A}$ $I_{OUT} = \pm 2.17 \text{ A to } \pm 1.09 \text{ A}$		4,5,6	01	 	0.5	ms	
changes 1/2/3/							0.5		
Output response to transient step line changes 1/4/	VTLINE	I _{OUT} = ±2. V _{IN} = 160	17 A, V dc to 400 V dc	4,5,6	01		500	mV pk	
changes		I _{OUT} = ±2. V _{IN} = 400	.17 A, V dc to 160 V dc				500		
Recovery time, transient step line changes 1/3/4/	 TT _{LINE}	I _{OUT} = ±2 V _{IN} = 160	.17 A, V dc to 400 V dc	4,5,6	01		100	μs	
changes <u>I</u> , <u>2</u> , I ,		I _{OUT} = ±2 V _{IN} = 400	.17 A, V dc to 160 V dc				100		
Isolation	ISO	500 V dc	 		01	100		ΜΩ	
			input to case			100			
			output to case			100			
See footnotes at end o	f table.								
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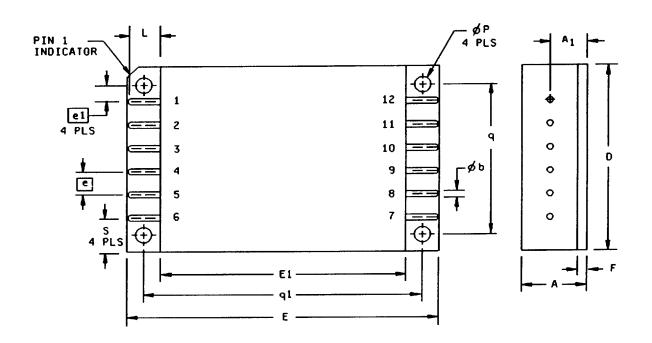
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Test	Symbol	Conditions $\begin{array}{ccc} & & & & & & \\ & & -55^{\circ}C \leq T_{C} \leq +125^{\circ}C \\ & & & & & & & & & & & & & & & & \\ & & & & $	Group A subgroups	Device type	(imits.	Unit —
		V _{IN} = 270 V dc ± 1 V dc no external sync unless otherwise specified	 	! ! !	 Min 	Max	
Sync. range <u>5</u> /	 sync	 I _{OUT} = ±2.17 A	4,5,6	01	525	675	kHz
Capacitive load 1/6/	cL	 No effect on dc performance	1	01		500	μF

- 1/ Parameter shall be tested as part of design characterization and after design or process changes; therefore, the Parameter shall be guaranteed to limits specified in table I.
- 2/ Load step transition time between 2 and 10 microseconds.
- 3/ Recovery time is measured from the initiation of the transient until V_{OUT} has returned to within ±1 percent of its final value.
- 4/ Transition time greater than 10 microseconds.
- $\frac{5}{4}$ A TTL level waveform (V_{IH} = 4.5 V minimum, V_{IL} = 0.8 V maximum) with a 50 percent ±10 percent duty cycle applied to the sync input pin (pin 6) within the the sync range frequency shall cause the converter's switching frequency to become synchronous with the frequency applied to the sync input pin (pin 6).
- 6/ Capacitive load may be any value from 0 to the maximum limit without compromising dc performance.
- 7/ No more than 80 percent of the maximum output current can be delivered from a single output.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		5962-95564
DAYTON, OHIO 45444		REVISION LEVEL	SHEET 7

9004708 0013069 883 📼



Symbol	Mill	imeters	Inc	ches
•	Min	Max	Min	Max
Α		10.16		.400
A1	5.44	5.74	.214	.226
φb	.89	1.14	.035	.045
D	37.97	38.23	1.495	1.505
е	5.08	BSC	.200	BSC
e1	3.30	BSC	.130	BSC
E	75.95	76.46	2.990	3.010_
E1	63.37	63.63	2.495	2.505
F	1.14	1.40	.045	.055
L	5.58	6.09	.220	.240
ФΡ	3.12	3.38	.123	.133
q	31.88	32.13	1.255	1.265_
q1	69.97	70.23	2.755	2.765
S	6.20	6.50	.244	. 256

NOTES:

- The case outline X was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound shall take precedence.
- 2. Device weight: 86 grams maximum.

FIGURE 1. Case outline.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-95564
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 8

DESC FORM 193A JUL 94

9004708 0013070 5T5 🔤

Device type	01
Case outline	x
Terminal number	Terminal symbol
1	Input
2	Input return
3	Inhibit 2
4	Inhibit 1
5	Sync output
6	Sync input
7	Positive output
8	Output return
9	Negative output
10	No connection
11	No connection
12	Share

NOTES:

- Multiple devices may be used in parallel to drive a common load. When using this mode of operation the load current is shared up to five devices. In the current sharing mode, the share pin (pin 12) of all devices are connected together.
- 2. The device has a sync input pin (pin 6) and a sync output pin (pin 5) which allows multiple devices, whether their in a single unit or master/slave configurations to be synchronized to a system clock or each other. Two or more devices may be synchronized to each other by connecting the sync output pin (pin 5) of one to the sync input pin (pin 6) of another.
- 3. The device has two inhibit options, one is ground referenced to the input common and the other is referenced to the output common. The output referred inhibit pin uses the inhibit 2 pin (pin 3) a TTL compatiable open collector low will inhibit the device when applied to this pin.

FIGURE 2. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95564
		REVISION LEVEL	SHEET 9

DESC FORM 193A JUL 94

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TABLE II. Electrical test requirements.

MIL-H-38534 test requirements	Subgroups (in accordance with MIL-H-38534, group A test table)	
Interim electrical parameters		
Final electrical test parameters	1*, 2, 3, 4, 5, 6	
Group A test requirements	1, 2, 3, 4, 5, 6	
Group C end-point electrical parameters	1	
MIL-STD-883, group E end-point electrical parameters for RHA devices	Subgroups ** (in accordance with method 5005, group A test table)	

- * PDA applies to subgroup 1.
- ** When applicable to this standardized military drawing, the subgroups shall be defined.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-H-38534 and as specified herein.
 - 4.3.1 Group A inspection. Group A inspection shall be in accordance with MIL-H-38534 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.
 - 4.3.2 Group B inspection. Group B inspection shall be in accordance with MIL-H-38534.
 - 4.3.3 Group C inspection. Group C inspection shall be in accordance with MIL-H-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DESC-EC or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
 - 4.3.4 Group D inspection. Group D inspection shall be in accordance with MIL-H-38534.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95564
		REVISION LEVEL	SHEET 10

- 4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes H and K shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.
 - a. RHA tests for device classes H and K for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
 - b. End-point electrical parameters shall be as specified in table II herein.
 - c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
 - d. For device classes H and K, the devices shall be subjected to radiation hardness assured tests as specified in MIL-H-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5 percent, after exposure.
 - e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
 - f. For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
 - g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.
 - 5. PACKAGING
 - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-H-38534.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC~EC, Dayton, Ohio 45444, or telephone (513) 296-5373.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95564
		REVISION LEVEL	SHEET 11

6.6 One part — one part number system. The one part — one part number system described below has been developed to allow for transitions between identical generic devices covered by the three major microcircuit requirements documents (MIL—H—38534, MIL—I—38535, and 1.2.1 of MIL—STD—883) without the necessity for the generation of unique PIN's. The three military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all three documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

Military documentation format	Example PIN under new system	Manufacturing source listing	Document <u>listing</u>
New MIL-H-38534 Standardized Microcircuit Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Microcircuit Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Microcircuit Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 <u>Sources of supply for device classes H and K</u>. Sources of supply for device classes H and K are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DESC-EC and have agreed to this drawing.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95564
		REVISION LEVEL	SHEET 12

DESC FORM 193A JUL 94

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